

# **SLP SERIES**

5 to 10kV, 450 to 1000mA, 75nS Surface Mount Diodes



#### **Features**

- Long Surface Mount Package
- J Lead or Gullwing Package Option
- Available in Cut Tape and 1000 Piece Reels
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

### Specifications<sup>1</sup>

Part Number	V <sub>RRM</sub> V	I <sub>FAVM1</sub> 2 mA	I <sub>FAVM2</sub> 2 mA	I <sub>FAVM3</sub> <sup>2</sup> mA	V <sub>F</sub> V	l <sub>R</sub> μΑ	I <sub>FSM</sub>	C <sub>J</sub> pF	T <sub>RR</sub> nS	R <sub>θJL</sub> °C/W	R <sub>θJC</sub> °C/W
J Lead Subseries (Figure 1)											
SLP05M	5000	1000	500	500	8.5	0.5	15	7.5	75	17	27
SLP10M	10000	450	230	300	15.8	0.5	15	3.7	75	17	27
Gullwing Subseries (Figure 2)											
SLP05MG	5000	1000	500	500	8.5	0.5	15	7.5	75	17	27
SLP10MG	10000	450	230	300	15.8	0.5	15	3.7	75	17	27

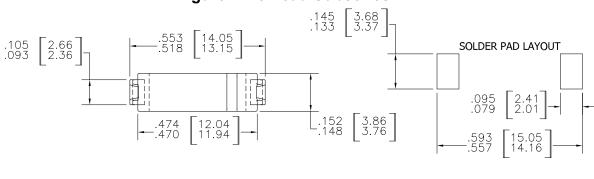
Temperature °C					
Operating Temperature	-55 to 150				
Storage Temperature	-55 to 175				
Maximum Junction Temperature	150				

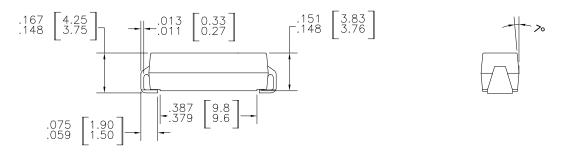
<sup>&</sup>lt;sup>1</sup>25°C ambient temperature unless stated otherwise.

#### **Drawings**

Dimensions in inches [mm], tolerances ±0.020 except as noted

## Figure 1 – J Lead Subseries





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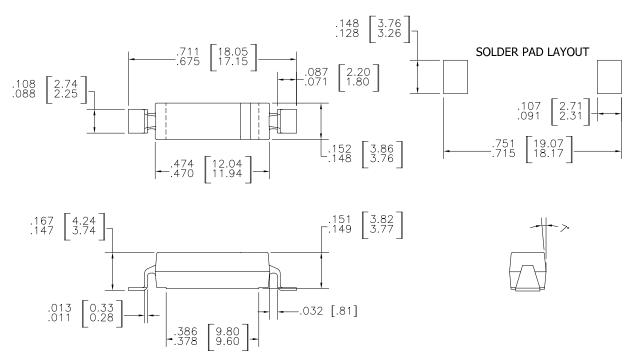
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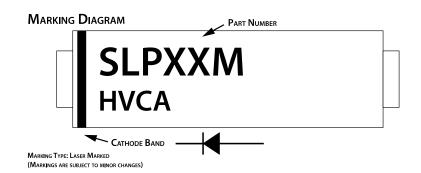
<sup>&</sup>lt;sup>2</sup>Check Specification Definitions for conditions details.

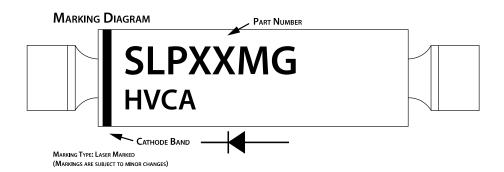


## **SLP SERIES**

Figure 2 – Gullwing Subseries







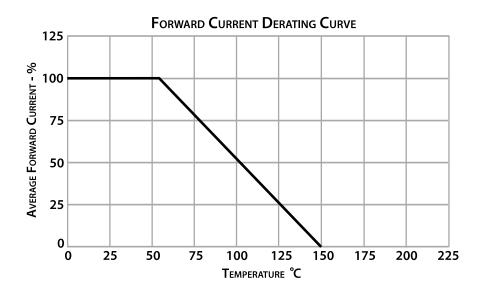
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## **Specification Definitions**

	Specifications	Conditions			
$V_{RRM}$	Maximum Repetitive Reverse Voltage	-			
I <sub>FAVM1</sub>	Maximum Average Forward Current	At T <sub>L</sub> = 55°C			
I <sub>FAVM2</sub>	Maximum Average Forward Current	At T <sub>L</sub> = 100°C			
I <sub>FAVM3</sub>	Maximum Average Forward Current	At $T_C = 80^{\circ}C$			
$V_{F}$	Maximum Forward Voltage Drop	At 200mA			
$I_R$	Maximum Leakage Current	At V <sub>RRM</sub>			
I <sub>FSM</sub>	Maximum Surge Current	At 8.3 mS, Single Half Sine			
CJ	Typical Junction Capacitance	At $V_R = 0VDC$ , $f = 1MHz$			
T <sub>RR</sub>	Maximum Reverse Recovery Time	$I_F = 100 \text{mA}$ ; $I_R = -200 \text{mA}$ ; $I_{RR} = -50 \text{mA}$			
$R_{\theta JL}$	Typical Thermal Resistance Junction to Lead	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads			
R <sub>0</sub> JC	Typical Thermal Resistance Junction to Case	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads			

ROHS

 $\label{thm:Note:Specifications subject to change without notice. Photo is representation only. \\$ 

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